News and agenda

ITS Upgrade Meeting, 29th November 2010

L. Musa

News

Participating Institutes

Institutes that already expressed their adhesion before last meeting

- Bari, Catania, CERN, Padua, Prague, Rome, Strasburg, Trieste, Turin
- St-Petersburg (wide interest but participation subject to some contingent political issue)

Institutes that joined since last meeting

- Kosice, Kharkov

Ongoing discussion with other institutes outside the present ITS collaboration

Synergy with other Experiments/Projects

- NA62 agreement for the R&D on thinning readout chip wafers
- CBM possible collaboration on strips and micro vertex detectors and multi-layer bus
- LHCB, MEDIPIX, ILC/CLIC on front-end electronics ⇨
    - various discussions
    - meetings being organized by CERN MIC to take place early next year

Agenda

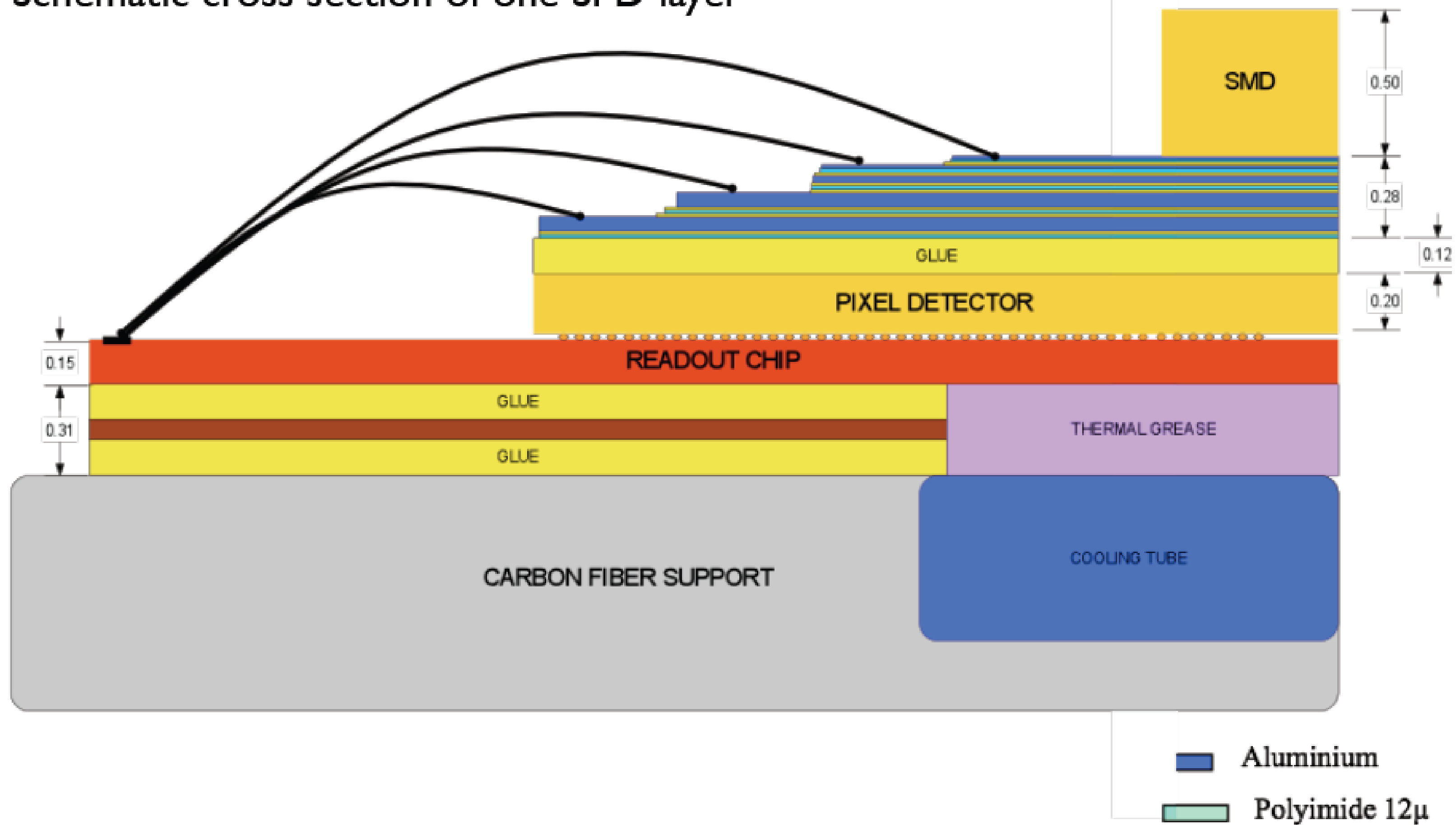
Plenary session

- Update on test beam activities (Romualdo)
- Update on simulation tools (Cristina)
- Multilayer light electrical bus (Rui)

WGs sessions: tasks and organization

Light multilayer electrical bus

P. Riedler
ITS Upgrade Meeting
4th October 2010



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In one SPD layer

- Carbon fiber support: 200 μm
- Cooling tube (Phynox): 40 μm wall thickness
- Grounding foil (Al-Kapton): 75 μm
- Pixel chip (Silicon): 150 μm ➡ 0.16%
- Bump bonds (Pb-Sn): diameter ~15-20 μm
- Silicon sensor: 200 μm ➡ 0.22%
- Pixel bus (Al+Kapton): 280 μm ➡ 0.48%
- SMD components
- Glue (Eccobond 45) and thermal grease

Two main contributors: silicon and interconnect structure (bus)